

### AMENDMENTS TO THE SPECIFICATION

Paragraph bridging pages 9 and 10:

B1 Referring to FIG. 1, a high-frequency current suppression body 15 has a granular magnetic thin film 19 consisting of  $\text{Fe}_a\text{A}_b\text{O}_c$  formed on one surface of either a synthetic resin sheet or film substrate 17 by sputtering. On top of the granular magnetic thin film 19, a synthetic resin coating 2 21 is provided for peeling away and reinforcing the granular magnetic thin film. On the other surface of the substrate 17, meanwhile, a bonding adhesive or pressure-sensitive adhesive layer 23 consisting of rubber of a synthetic resin or the like and, formed thereon, a peel-away sheet or removal sheet 25 are respectively provided. Here, the synthetic resin sheet or film substrate 17 may consist of any synthetic resin, such as polyethylene terephthalate (PET), polyester ether ketone (PEEK), or polyimide, etc., so long as it is not deformed during sputtering processing or vapor deposition. For the bonding adhesive used for the bonding adhesive or pressure-sensitive adhesive layer 23, a solvent system or emulsion system resin, such as an acrylic acid ester, polyvinyl ether, polyvinyl acetate, polystyrene, or polyvinyl butyral resin can be used. For the tacky adhesive, those same resins to which a tackifier containing rosin or a derivative thereof, terpene resin or other terpene derivative, and a cyclopentadiene, styrene, phenol, xylene, or coumarone-indene resin, or a silicone, polyurethane, fluorine, or acrylic rubber may be used, with that wherein fire-retardant, insulative, flexible silicone rubber is used being particularly preferable, but any bonding adhesive or tacky adhesive whatever can be used which has sufficient adhesive strength not to peel away from the synthetic resin sheet or film substrate configuring the substrate 2 17.

First full paragraph at page 10:

B2 For the peel-away sheet 25, either a surface-treated paper or resin or the like can be used so long as it can be easily peeled away from the adhesive surface. And for the synthetic resin coating 5 28, anything can be used so long as it forms a comparatively elastic synthetic resin layer when applied and dried. Alternatively, a thermoplastic resin sheet may be pressed on under heat.

First full paragraph at page 11:

B3 Referring to FIG. 4, a high-frequency current suppression body 33 according to a second embodiment of the present invention has a granular magnetic thin film 19 consisting of  $\text{Fe}_a\text{A}_b\text{O}_y$ , formed by sputtering on one surface of a synthetic resin sheet or film substrate 35. On top of the granular magnetic thin film 19, a synthetic resin layer substrate 37 is formed by application applying and drying ~~which has a similar composition as described~~. Adhesive layers 39 and 41 are deployed on each surface. On the adhesive layers 39 and 41, peel-away sheets 43 and 45 are severally deployed. Accordingly, the high-frequency current suppression body 33 is formed which has an adhesive layer on both sides thereof. For the synthetic resin layers 43 and 45 and the adhesive layers 39 and 41, the same materials as were used in the first embodiment can be used.

#### IN THE DRAWINGS

A proposed substitution for Fig. 7C is submitted on a separate sheet.